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TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

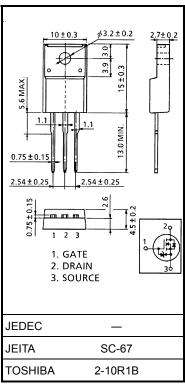
# 2SK2545

## DC-DC Converter, Relay Drive and Motor Drive Applications

- Low drain-source ON resistance  $: RDS (ON) = 0.9 \Omega(typ.)$
- High forward transfer admittance  $|Y_{fs}| = 5.5 \text{ S (typ.)}$
- Low leakage current  $: IDSS = 100 \ \mu A \ (max) \ (VDS = 600 \ V)$
- Enhancement mode :  $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$

#### Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	600	V	
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	600	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	6	А	
	Pulse (Note 1)	I <sub>DP</sub>	24	А	
Drain power dissipation	n (Tc = 25°C)	PD	40	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	345	mJ	
Avalanche current		I <sub>AR</sub>	6	А	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	4	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	



Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.125	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	62.5	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 16.8 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 6 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm

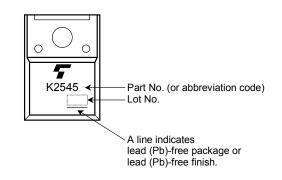
#### Electrical Characteristics (Ta = 25°C)

Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Gate-source br	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, V_{GS} = 0 \ V$	±30	_		V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>DS</sub> = 0 V		_	100	μA
Drain-source bi	reakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_		V
Gate threshold	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A		0.9	1.25	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	2.0	5.5		S
Input capacitance		C <sub>iss</sub>		_	1300	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		Coss			400	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \int I_{D} = 3A \\ V_{OU} \int R_{L} = 100\Omega$		25		- ns
	Turn-on time	t <sub>on</sub>		_	45	_	
	Fall time	t <sub>f</sub>		_	40	_	
	Turn-off time	t <sub>off</sub>	$V_{DD}$ ⇒ 300V Duty ≤1%, t <sub>w</sub> =10µs	_	150	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	30	_	nC
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	_	18	—	
Gate-drain ("miller") charge		Q <sub>gd</sub>			12	—	]

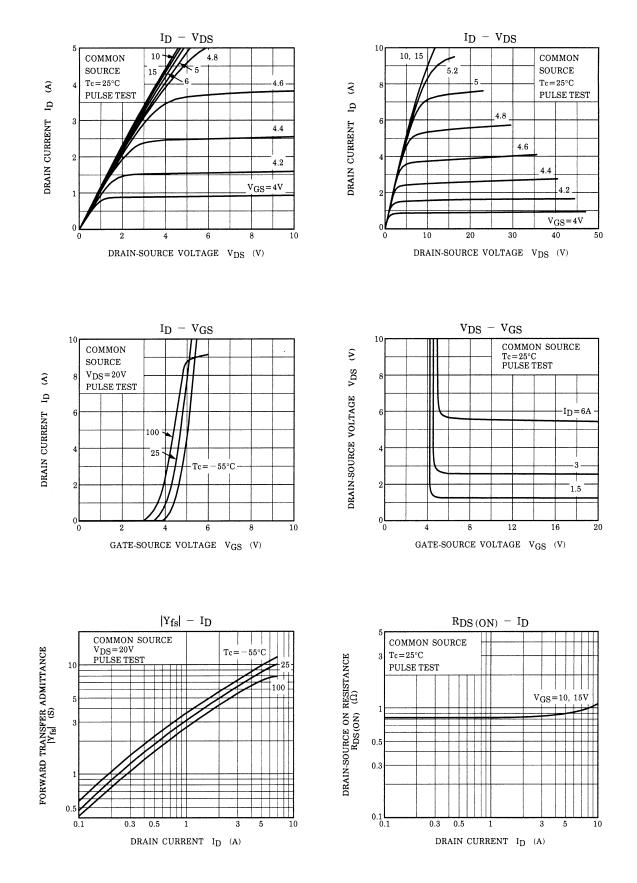
#### Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	—	_	_	6	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	—	_	_	24	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	l <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V, dl <sub>DR</sub> / dt = 100 A / μs		1000	_	ns
Reverse recovery charge	Q <sub>rr</sub>		_	7.0	_	μC

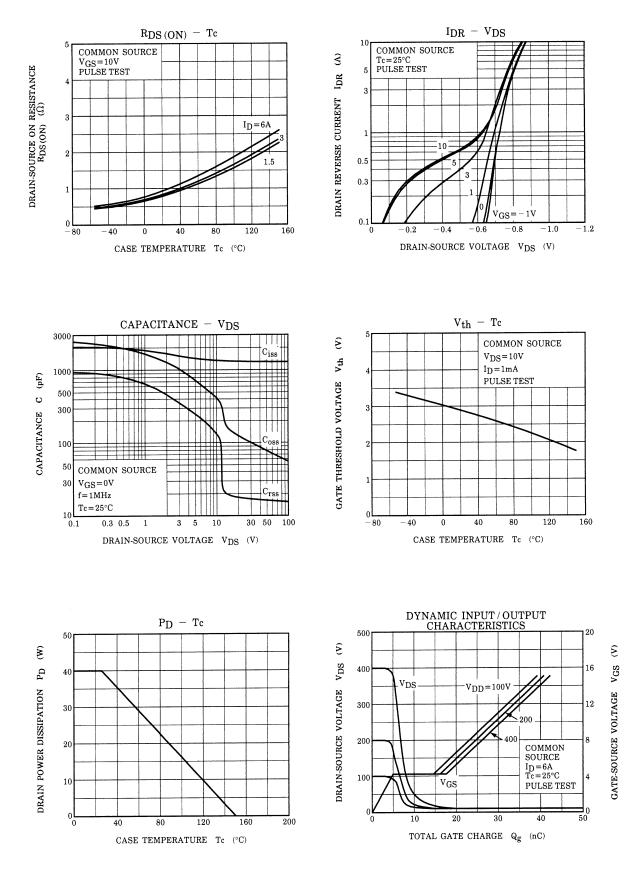
#### Marking

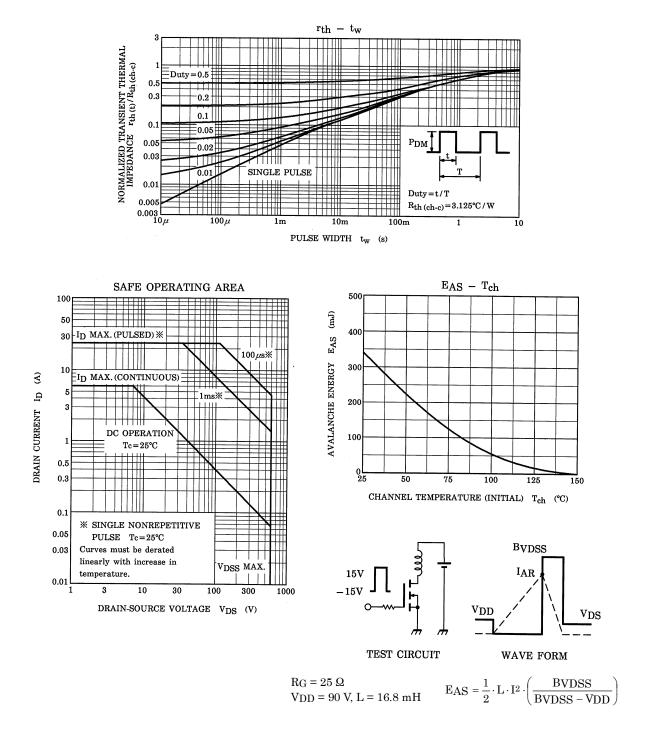


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